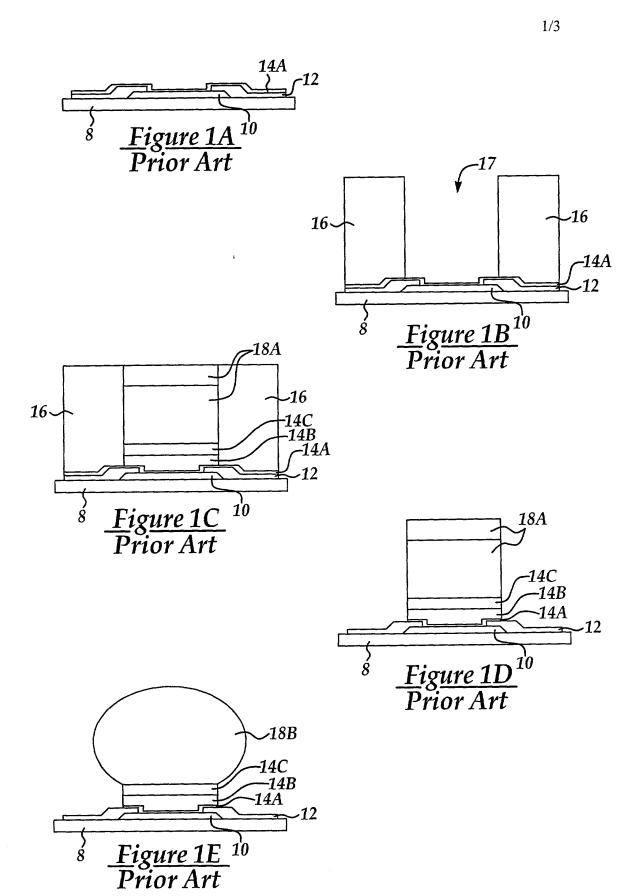
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Attorney Docket No.: 67,200-630

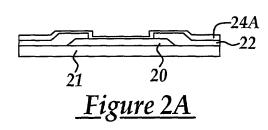


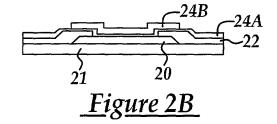
Inventor(s): Su, et al Serial No.: To Be Assigned Filed: Herewith

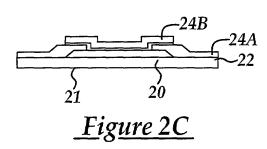
Method Of Forming A Solder Ball Using A Thermally ... Layer

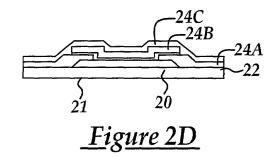
Attorney Docket No.: 67,200-630

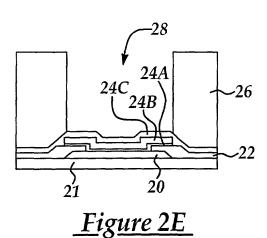
2/3

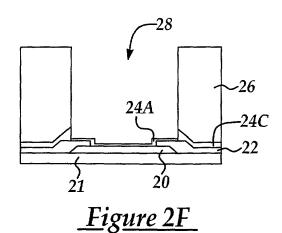








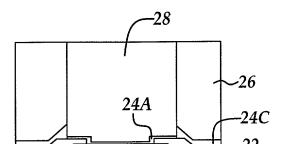




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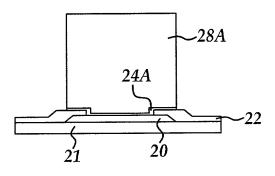
Attorney Docket No.: 67,200-630



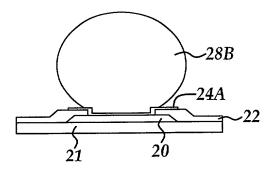
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<u>Figure 3A</u>



<u>Figure 3B</u>



<u>Figure 3C</u>